- **Low $r_{DS(on)}$:**
  0.25 Ω Typ (Full H-Bridge)
  0.4 Ω Typ (Triple Half H-Bridge)
- **Pulsed Current . . . 4 A Per Channel**
- **Matched Sense Transistors for Class A-B Linear Operation**
- **Fast Commutation Speed**

DW PACKAGE
(TOP VIEW)

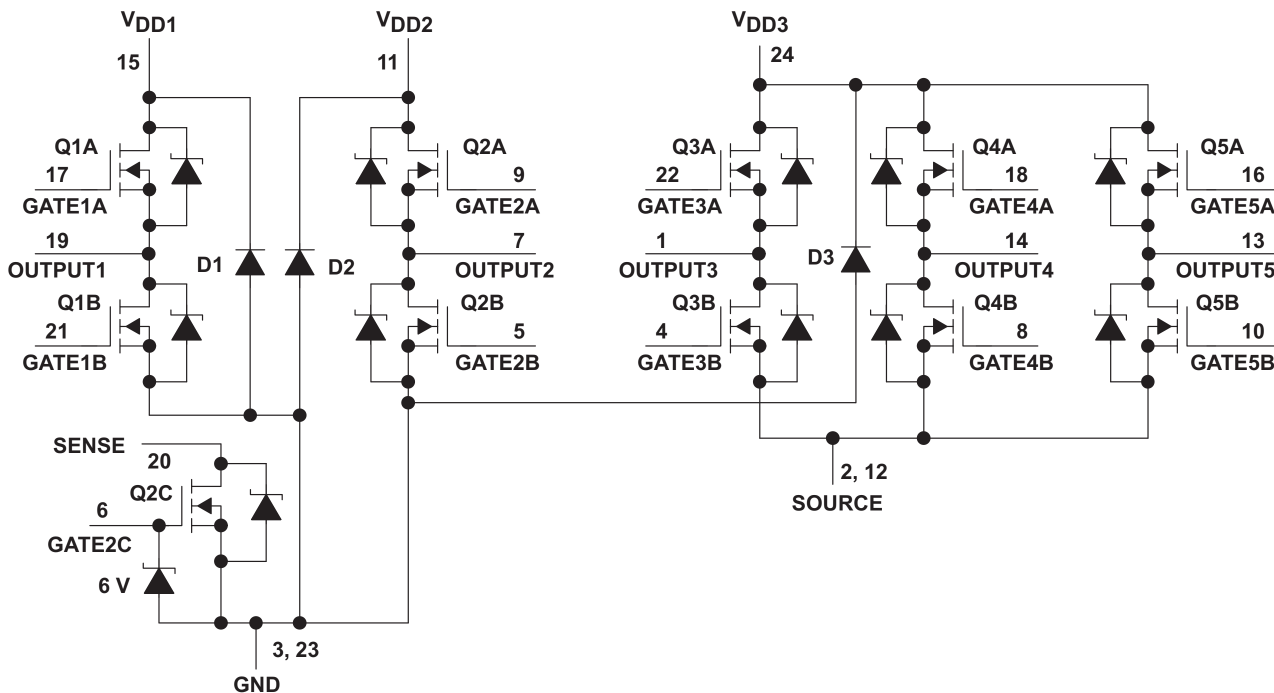
Pin name	Pin	Pin	Pin name
OUTPUT3	1	24	V_{DD3}
SOURCE	2	23	GND
GND	3	22	GATE3A
GATE3B	4	21	GATE1B
GATE2B	5	20	SENSE
GATE2C	6	19	OUTPUT1
OUTPUT2	7	18	GATE4A
GATE4B	8	17	GATE1A
GATE2A	9	16	GATE5A
GATE5B	10	15	V_{DD1}
V_{DD2}	11	14	OUTPUT4
SOURCE	12	13	OUTPUT5

description

The TPIC1502 is a monolithic power DMOS array that consists of ten electrically isolated N-channel enhancement-mode power DMOS transistors, four of which are configured as a full H-bridge and six as a triple half H-bridge. The lower stage of the full H-bridge is provided with an integrated sense-FET to allow biasing of the bridge in class A-B operation.

The TPIC1502 is offered in a 24-pin wide-body surface-mount (DW) package and is characterized for operation over the case temperature range of –40°C to 125°C.

schematic



NOTES: A. Terminals 3 and 23 must be externally connected.
B. Terminals 2 and 12 must be externally connected.
C. No output may be taken greater than 0.5 V below GND.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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absolute maximum ratings, T_C = 25°C (unless otherwise noted)†

Supply-to-GND voltage	20 V
Source-to-GND voltage (Q3A, Q4A, Q5A)	20 V
Output-to-GND voltage	20 V
Sense-to-GND voltage	20 V
Gate-to-source voltage range, V_{GS} (Q1A, Q1B, Q2A, Q2B, Q3A, Q3B, Q4A, Q4B, Q5A, Q5B)	±20 V
Gate-to-source voltage, V_{GS} (Q2C)	–0.7 V to 6 V
Continuous gate-to-source zener-diode current (Q2C)	±10 mA
Pulsed gate-to-source zener-diode current (Q2C)	±50 mA
Continuous drain current, each output (Q1A, Q1B, Q2A, Q2B)	1.5 A
Continuous drain current, each output (Q3A, Q3B, Q4A, Q4B, Q5A, Q5B)	1.5 A
Continuous drain current (Q2C)	5 mA
Continuous source-to-drain diode current (Q1A, Q1B, Q2A, Q2B)	1.5 A
Continuous source-to-drain diode current (Q3A, Q3B, Q4A, Q4B, Q5A, Q5B)	1.5 A
Continuous source-to-drain diode current (Q2C)	5 mA
Pulsed drain current, each output, I_{max} (Q1A, Q1B, Q2A, Q2B) (see Note 1 and Figure 24)	4 A
Pulsed drain current, each output, I_{max} (Q3A, Q3B, Q4A, Q4B, Q5A, Q5B) (see Note 1 and Figure 25)	4 A
Pulsed drain current, each output, I_{max} (Q2C) (see Note 1)	20 mA
Continuous total power dissipation, T_C = 70°C (see Note 2 and Figures 24 and 25)	2.86 W
Operating virtual junction temperature range, T_J	–40°C to 150°C
Operating case temperature range, T_C	–40°C to 125°C
Storage temperature range, T_{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Pulse duration = 10 ms, duty cycle = 2%
2. Package mounted in intimate contact with infinite heat sink.

electrical characteristics, Q1A, Q1B, Q2A, Q2B, T_C = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$V_{(BR)DSX}$	Drain-to-source breakdown voltage	I_D = 250 µA, V_{GS} = 0		20			V
$V_{GS(th)}$	Gate-to-source threshold voltage	I_D = 1 mA, $V_{DS} = V_{GS}$, See Figure 5		1.5	1.85	2.2	V
$V_{GS(th)match}$	Gate-to-source threshold voltage matching	I_D = 1 mA, $V_{DS} = V_{GS}$				40	mV
$V_{(BR)}$	Reverse drain-to-GND breakdown voltage	Drain-to-GND current = 250 µA (D1, D2)		20			V
$V_{(BR)GS}$	Gate-to-source breakdown voltage, Q2C	I_{GS} = 100 µA		6			V
$V_{(BR)SG}$	Source-to-gate breakdown voltage, Q2C	I_{GS} = 100 µA		0.7			V
$V_{(DS)on}$	Drain-to-source on-state voltage	I_D = 1.5 A, V_{GS} = 10 V, See Notes 3 and 4			0.375	0.45	V
V_F	Forward on-state voltage, GND-to-V_{DD1}, GND-to-V_{DD2}	I_D = 1.5 A (D1, D2) See Notes 3 and 4			1.5		V
$V_{F(SD)}$	Forward on-state voltage, source-to-drain	I_S = 1.5 A, V_{GS} = 0, See Notes 3 and 4 and Figure 19			0.93	1.2	V
I_{DSS}	Zero-gate-voltage drain current	V_{DS} = 16 V, V_{GS} = 0	T_C = 25°C		0.05	1	µA
			T_C = 125°C		0.5	10	
I_{GSSF}	Forward gate current, drain short-circuited to source	V_{GS} = 16 V, V_{DS} = 0			10	100	nA
I_{GSSR}	Reverse gate current, drain short-circuited to source	V_{SG} = 16 V, V_{DS} = 0			10	100	nA
I_{lkg}	Leakage current, V_{DD1}-to-GND, V_{DD2}-to-GND, gate shorted to source	V_{DGND} = 16 V	T_C = 25°C		0.05	1	µA
			T_C = 125°C		0.5	10	
$r_{DS(on)}$	Static drain-to-source on-state resistance	V_{GS} = 10 V, I_D = 1.5 A, See Notes 3 and 4 and Figure 9	T_C = 25°C		0.25	0.3	Ω
			T_C = 125°C		0.38	0.51	
g_{fs}	Forward transconductance	V_{DS} = 14 V, I_D = 750 mA, See Notes 3 and 4 and Figure 13		0.75	1.2		S
C_{iss}	Short-circuit input capacitance, common source	V_{DS} = 14 V, V_{GS} = 0, f = 1 MHz, See Figure 17			98		pF
C_{oss}	Short-circuit output capacitance, common source				70		
C_{rss}	Short-circuit reverse transfer capacitance, common source				54		
α_s	Sense-FET drain current ratio	V_{DS} = 6 V, $I_{D(Q2B)}$ = 1.5 mA		100	150	200	

NOTES: 3. Technique should limit $T_J - T_C$ to 10°C maximum.
4. These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts.

source-to-drain diode characteristics, Q1A, Q2A, T_C = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{rr}	Reverse-recovery time	I_S = 750 mA, V_{GS} = 0, V_{DS} = 14 V, di/dt = 100 A/µs, See Figures 1 and 23		18		ns
Q_{RR}	Total diode charge			14		nC

resistive-load switching characteristics, Q1A, Q1B, Q2A, Q2B, T_C = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{d(on)}$	Turn-on delay time	V_{DD} = 14 V, R_L = 18.7 Ω, t_{en} = 10 ns, t_{dis} = 10 ns, See Figure 3		12		ns
$t_{d(off)}$	Turn-off delay time			13		
t_r	Rise time			2.2		
t_f	Fall time			6		
Q_g	Total gate charge	V_{DS} = 14 V, I_D = 750 mA, V_{GS} = 10 V, See Figure 4 and Figure 21		1.7	2.1	nC
$Q_{gs(th)}$	Threshold gate-to-source charge			0.3	0.4	
Q_{gd}	Gate-to-drain charge			0.4	0.5	
L_D	Internal drain inductance			7		nH
L_S	Internal source inductance			7		
R_g	Internal gate resistance			0.25		Ω

electrical characteristics, Q3A, Q3B, Q4A, Q4B, Q5A, Q5B, T_C = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$V_{(BR)DSX}$	Drain-to-source breakdown voltage	I_D = 250 µA, V_{GS} = 0		20			V
$V_{GS(th)}$	Gate-to-source threshold voltage	I_D = 1 mA, V_{DS} = V_{GS}, See Figure 6		1.5	1.85	2.2	V
$V_{(BR)}$	Reverse drain-to-GND breakdown voltage	Drain-to-GND current = 250 µA (D3)		20			V
$V_{(DS)on}$	Drain-to-source on-state voltage	I_D = 1.5 A, V_{GS} = 10 V, See Notes 3 and 4			0.6	0.75	V
V_F	Forward on-state voltage, GND-to-V_{DD3}	I_D = 1.5 A (D3), See Notes 3 and 4			1.5		V
$V_{F(SD)}$	Forward on-state voltage, source-to-drain	I_S = 1.5 A, V_{GS} = 0 See Notes 3 and 4 and Figure 20			1	1.2	V
I_{DSS}	Zero-gate-voltage drain current	V_{DS} = 16 V, V_{GS} = 0	T_C = 25°C		0.05	1	µA
			T_C = 125°C		0.5	10	
I_{GSSF}	Forward gate current, drain short-circuited to source	V_{GS} = 16 V, V_{DS} = 0			10	100	nA
I_{GSSR}	Reverse gate current, drain short-circuited to source	V_{SG} = 16 V, V_{DS} = 0			10	100	nA
I_{lkg}	Leakage current, V_{DD3}-to-GND, gate shorted to source	V_{DGND} = 16 V	T_C = 25°C		0.05	1	µA
			T_C = 125°C		0.5	10	
$r_{DS(on)}$	Static drain-to-source on-state resistance	V_{GS} = 10 V, I_D = 1.5 A, See Notes 3 and 4 and Figure 10	T_C = 25°C		0.4	0.5	Ω
			T_C = 125°C		0.61	0.85	
g_{fs}	Forward transconductance	V_{DS} = 14 V, I_D = 750 mA, See Notes 3 and 4 and Figure 14		0.4	0.74		S
C_{iss}	Short-circuit input capacitance, common source	V_{DS} = 14 V, V_{GS} = 0, f = 1 MHz, See Figure 18			73		pF
C_{oss}	Short-circuit output capacitance, common source				65		
C_{rss}	Short-circuit reverse transfer capacitance, common source				43		

NOTES: 3: Technique should limit T_J – T_C to 10°C maximum.
4: These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts.

source-to-drain diode characteristics, Q3A, Q4A, Q5A, T_C = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{rr}	Reverse-recovery time	I_S = 750 mA, V_{GS} = 0, V_{DS} = 14 V, di/dt = 100 A/µs, See Figures 2 and 23		26		ns
Q_{RR}	Total diode charge			17		nC

resistive-load switching characteristics, Q3A, Q3B, Q4A, Q4B, Q5A, Q5B, T_C = 25°C

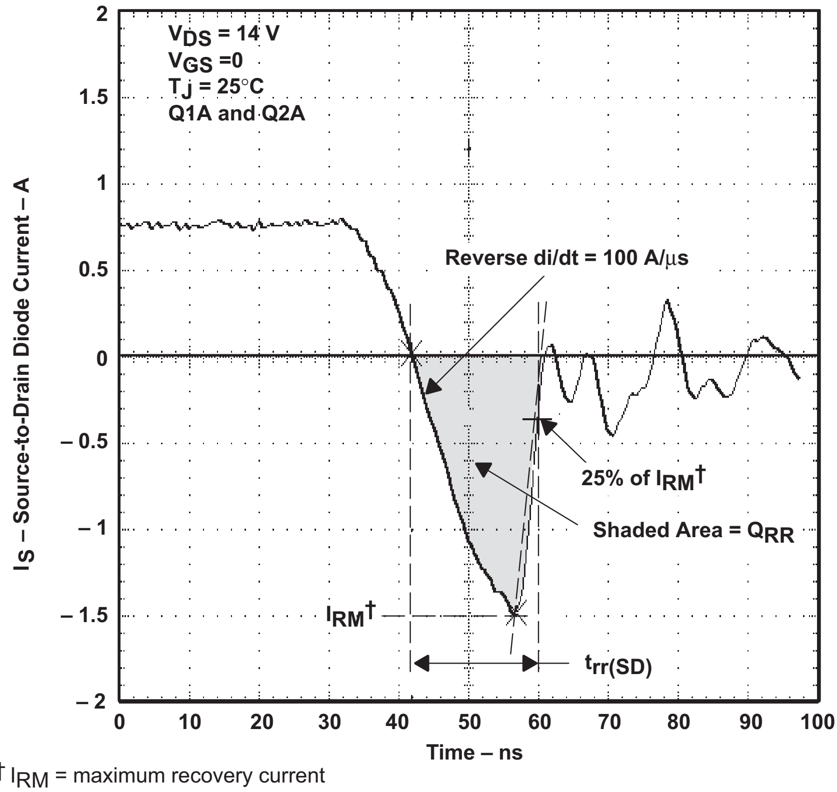
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{d(on)}$	Turn-on delay time	V_{DD} = 14 V, R_L = 18.7 Ω, t_{en} = 10 ns, t_{dis} = 10 ns, See Figure 3		13		ns
$t_{d(off)}$	Turn-off delay time			13		
t_r	Rise time			3		
t_f	Fall time			7		
Q_g	Total gate charge	V_{DS} = 14 V, I_D = 750 mA, V_{GS} = 10 V, See Figure 4 and Figure 22		1	1.3	nC
$Q_{gs(th)}$	Threshold gate-to-source charge			0.2	0.25	
Q_{gd}	Gate-to-drain charge			0.2	0.25	
L_D	Internal drain inductance			7		nH
L_S	Internal source inductance			7		
R_g	Internal gate resistance			0.25		Ω

thermal resistance

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	See Notes 5 and 8		90		°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	See Notes 6 and 8		52		
$R_{\theta JP}$	Junction-to-pin thermal resistance	See Notes 7 and 8		28		

NOTES: 5. Package mounted on a FR4 printed-circuit board with no heatsink.
6. Package mounted on a 24 in^2, 4-layer FR4 printed-circuit board.
7. Package mounted in intimate contact with infinite heatsink.
8. All outputs with equal power

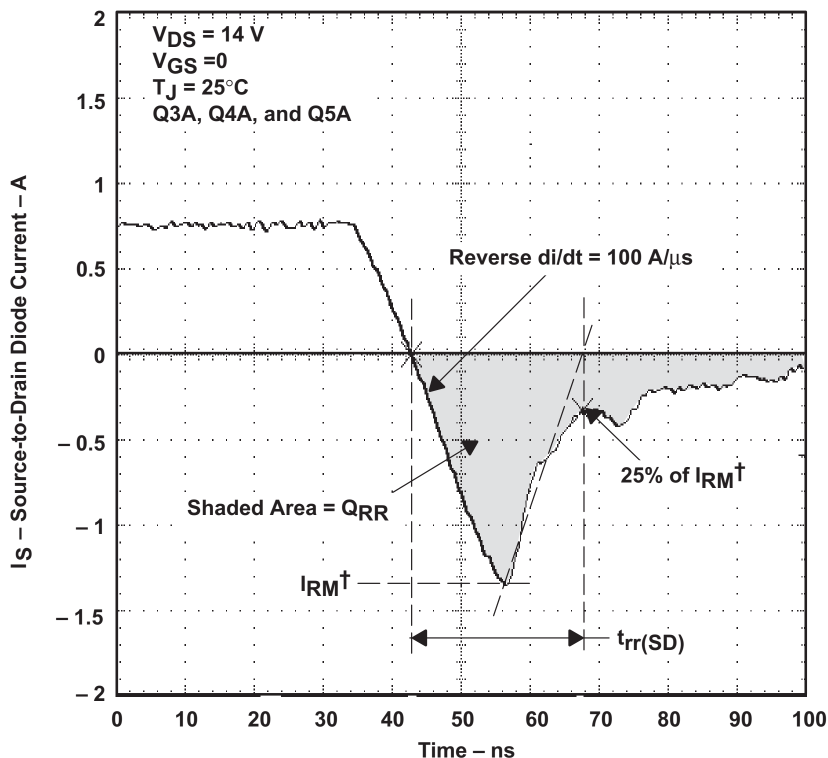
PARAMETER MEASUREMENT INFORMATION



† I_{RM} = maximum recovery current

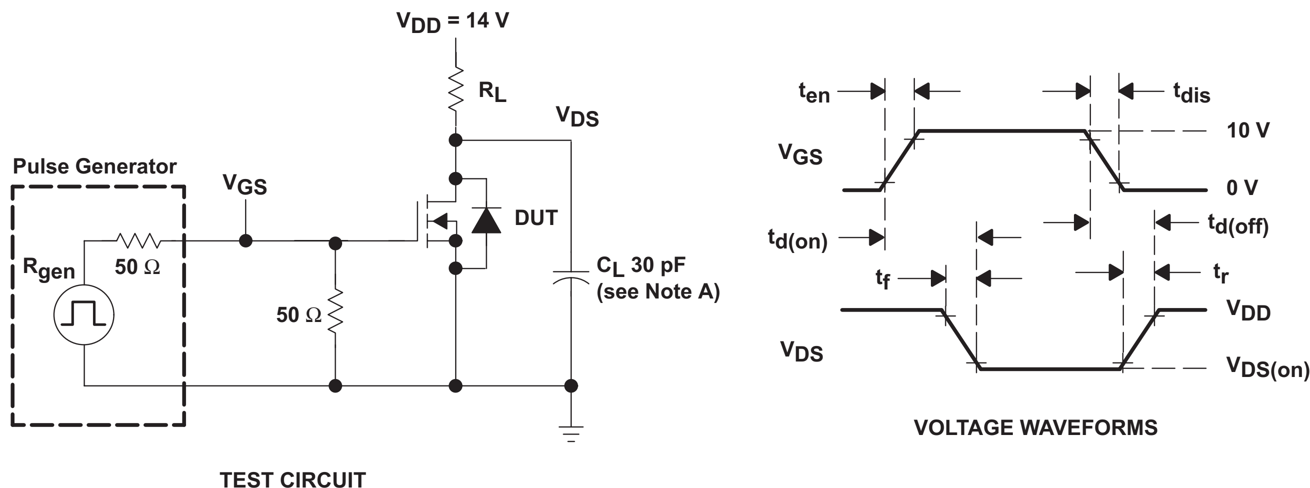
Figure 1. Reverse-Recovery-Current Waveform of Source-to-Drain Diodes

PARAMETER MEASUREMENT INFORMATION



† I_{RM} = maximum recovery current

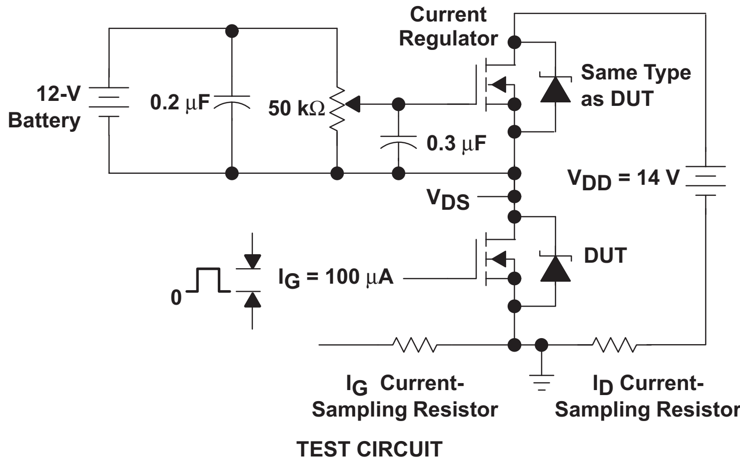
Figure 2. Reverse-Recovery-Current Waveform of Source-to-Drain Diodes



NOTE A: C_L includes probe and jig capacitance.

Figure 3. Resistive-Switching Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



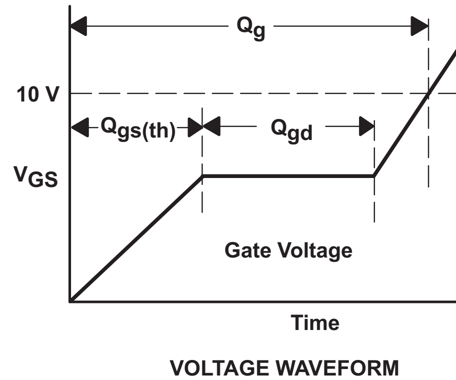


Figure 4. Gate-Charge Test Circuit and Voltage Waveform

TYPICAL CHARACTERISTICS

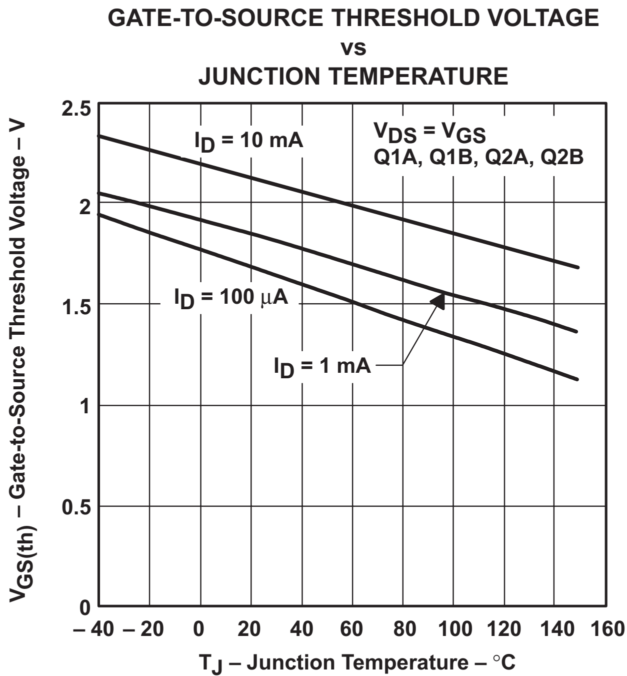


Figure 5

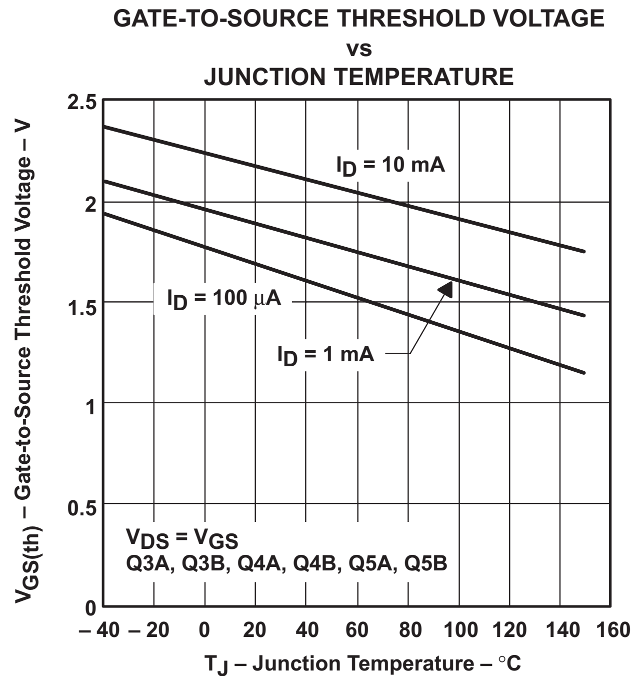


Figure 6

TYPICAL CHARACTERISTICS

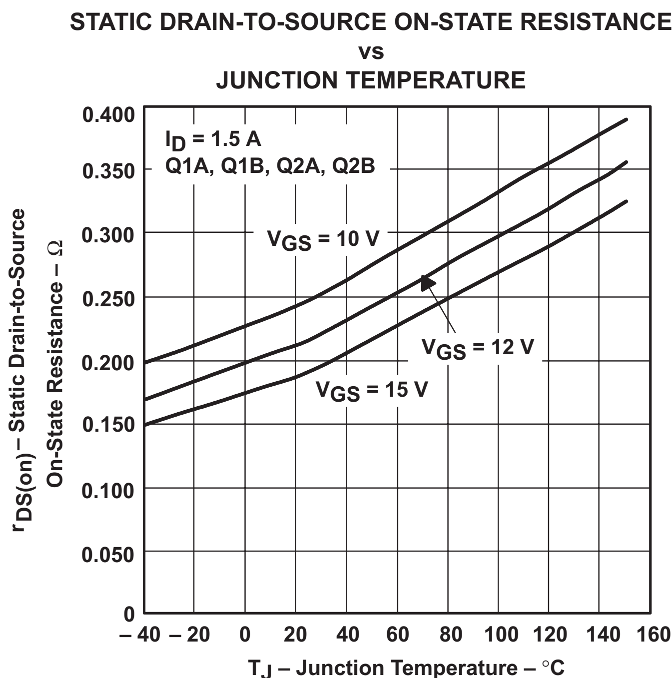


Figure 7

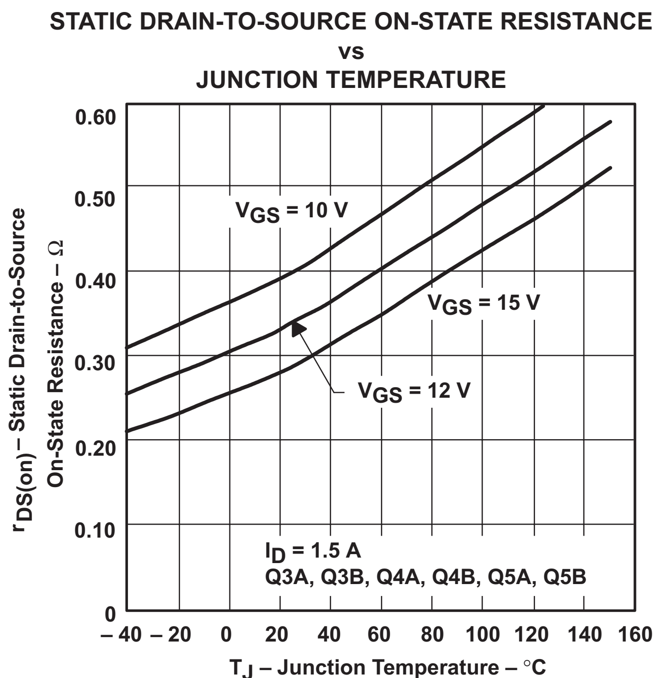


Figure 8

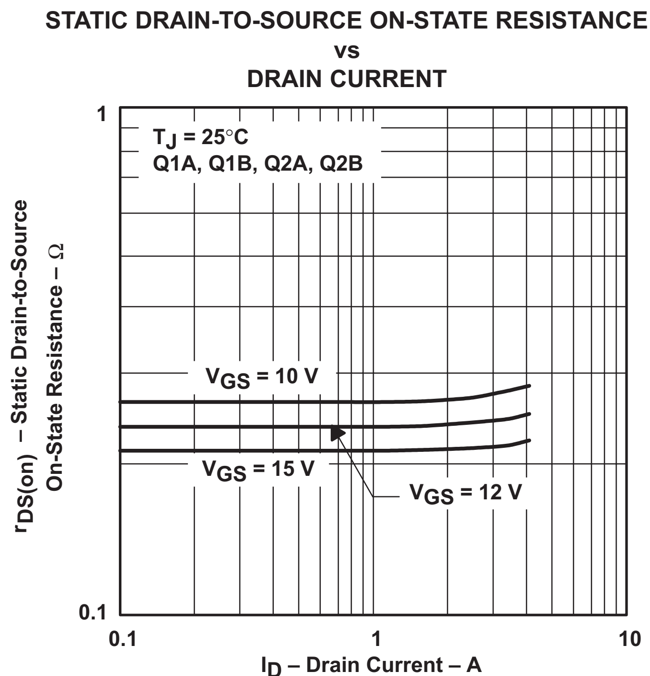


Figure 9

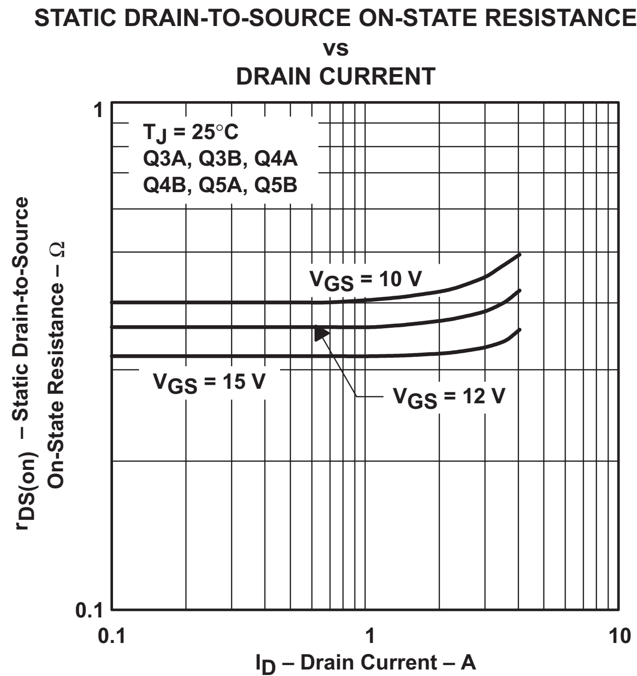


Figure 10

TYPICAL CHARACTERISTICS

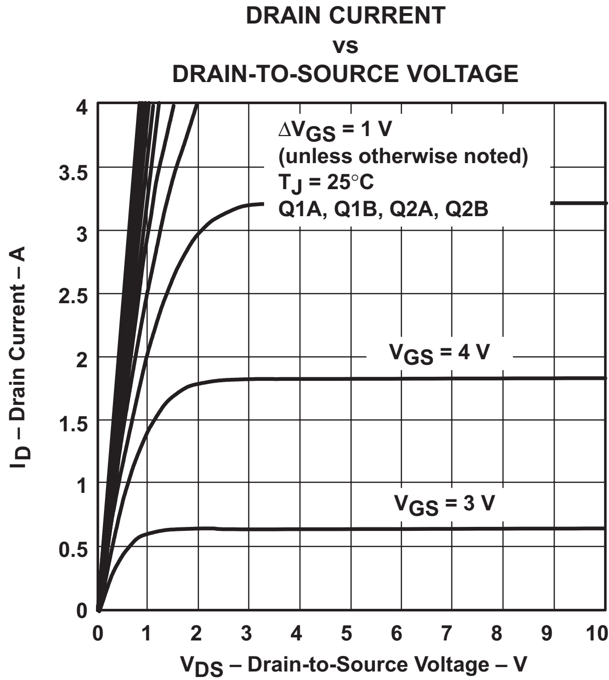


Figure 11

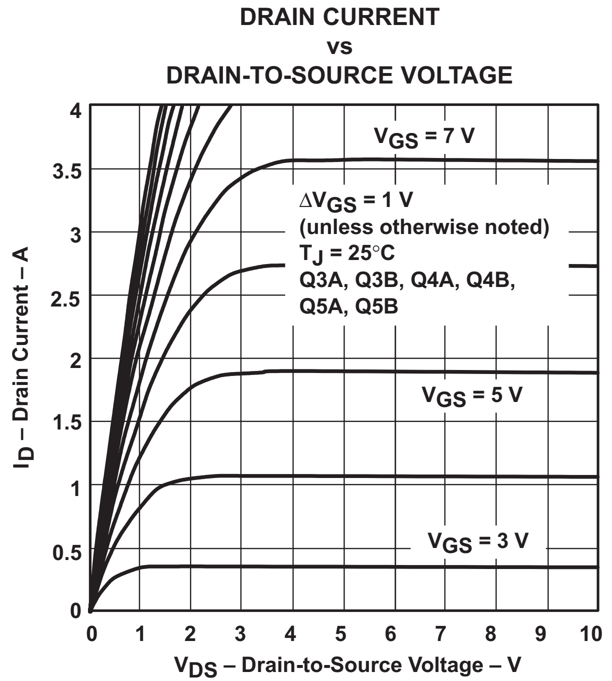


Figure 12

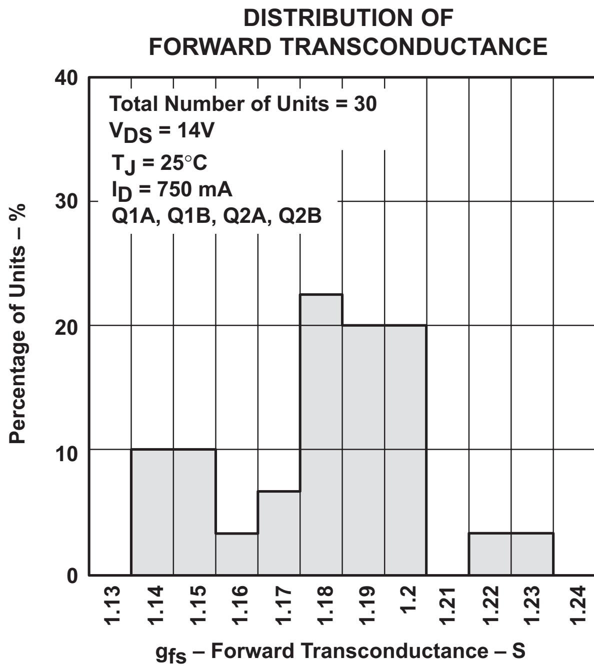


Figure 13

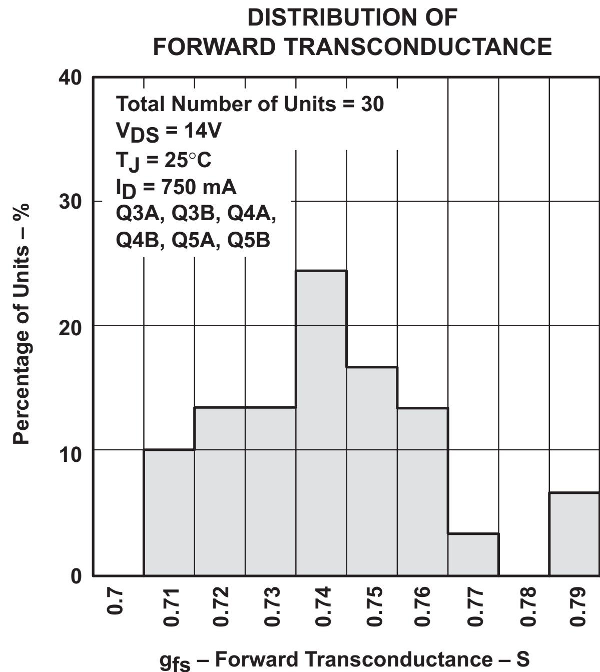


Figure 14

TYPICAL CHARACTERISTICS

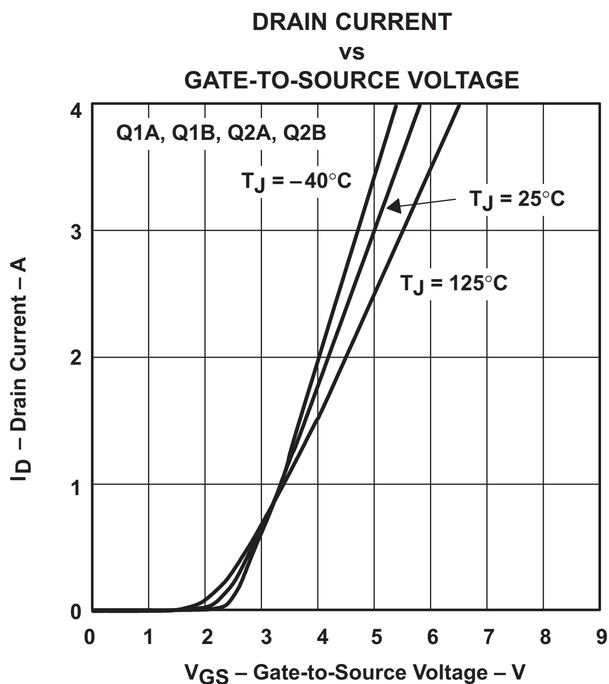


Figure 15

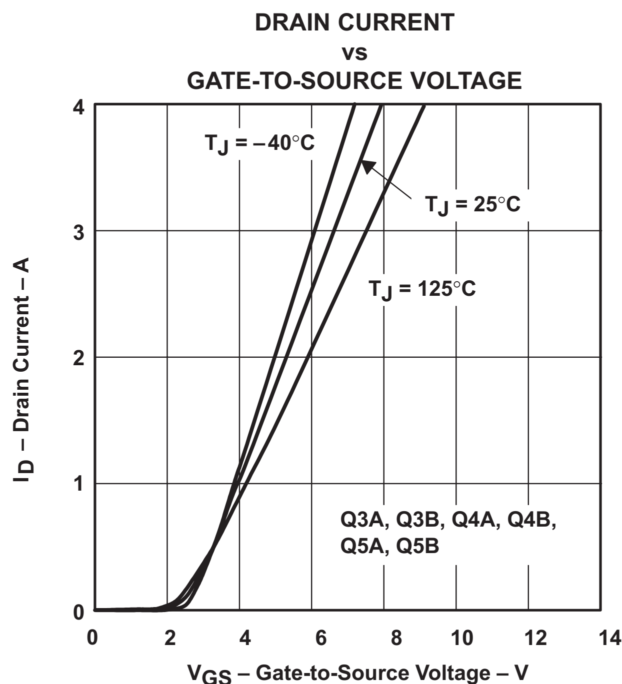


Figure 16

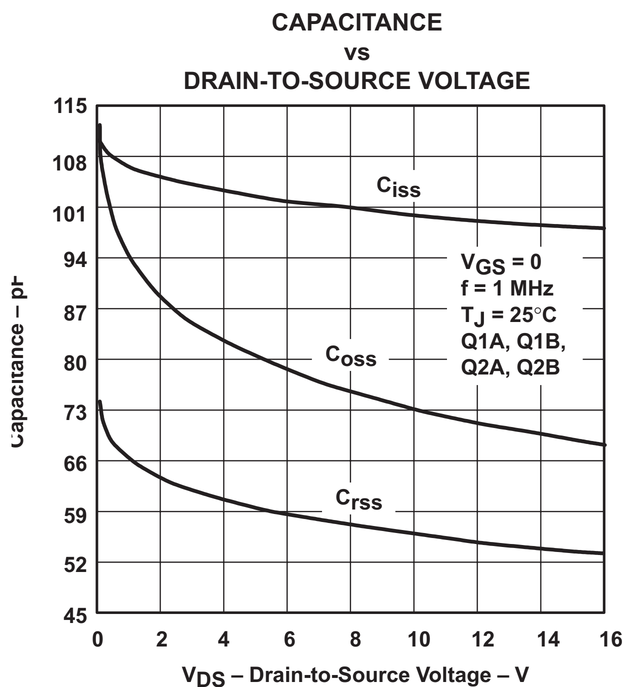


Figure 17

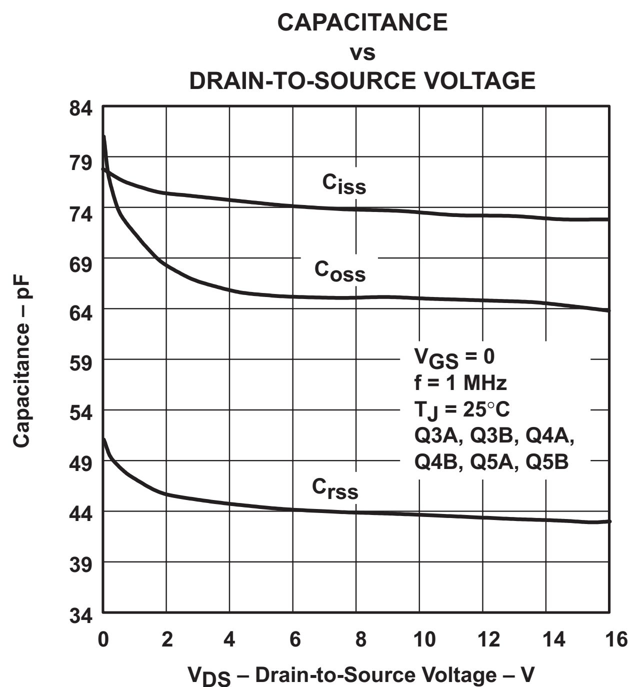


Figure 18

TYPICAL CHARACTERISTICS

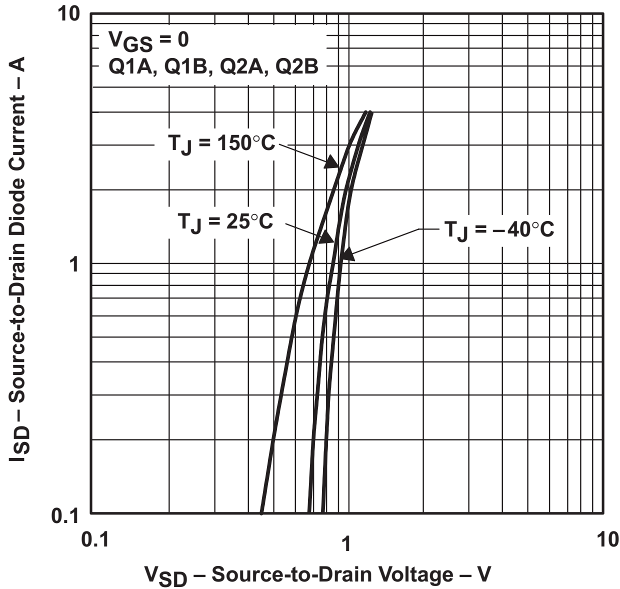


Figure 19

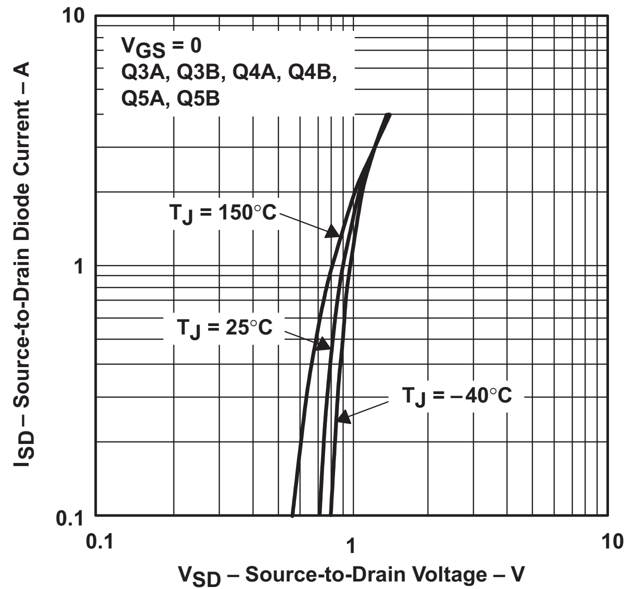


Figure 20

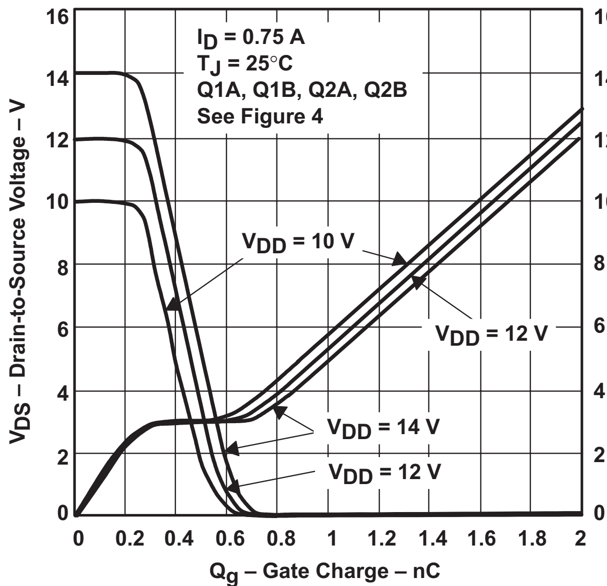


Figure 21

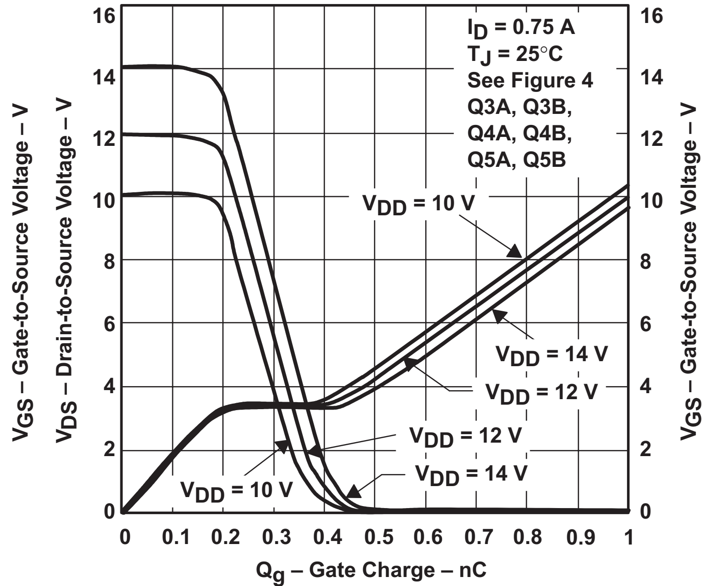


Figure 22

TYPICAL CHARACTERISTICS

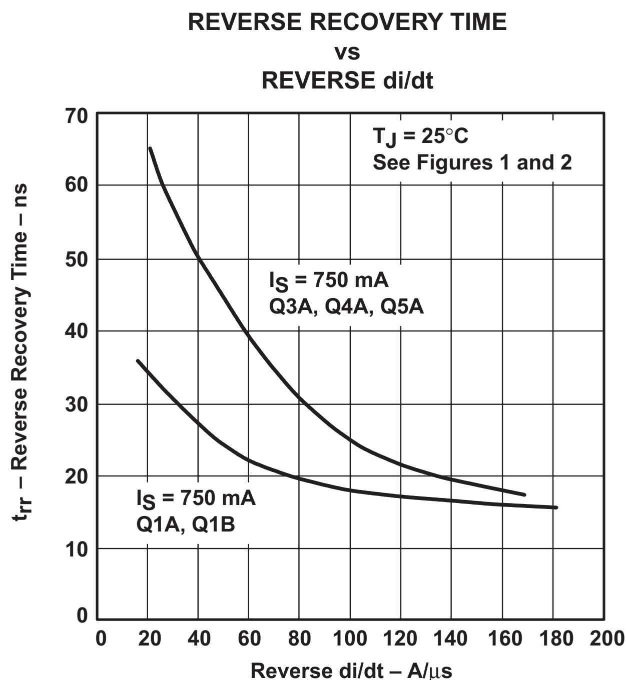


Figure 23

THERMAL INFORMATION

MAXIMUM DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE

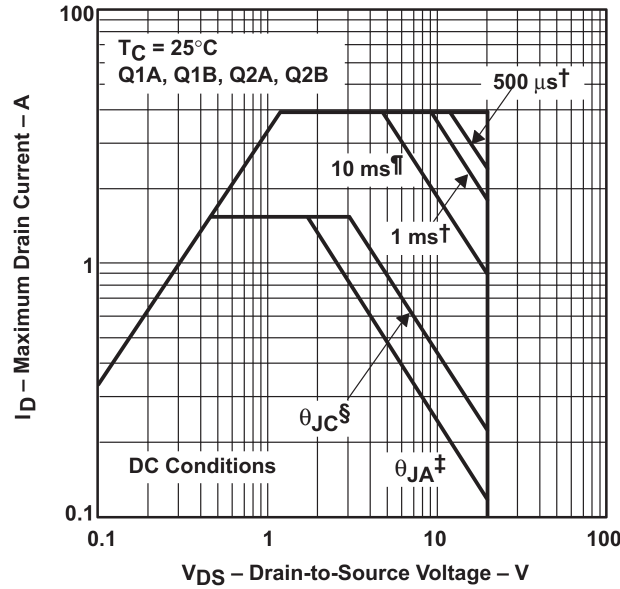


Figure 24

MAXIMUM DRAIN CURRENT vs DRAIN-TO-SOURCE VOLTAGE

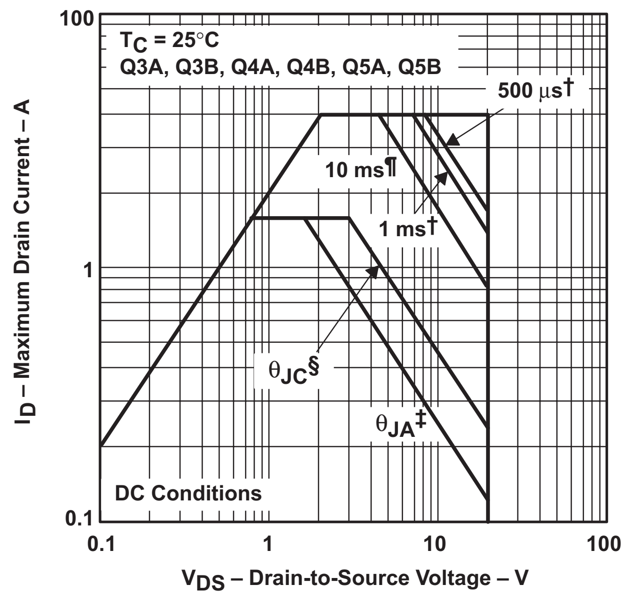
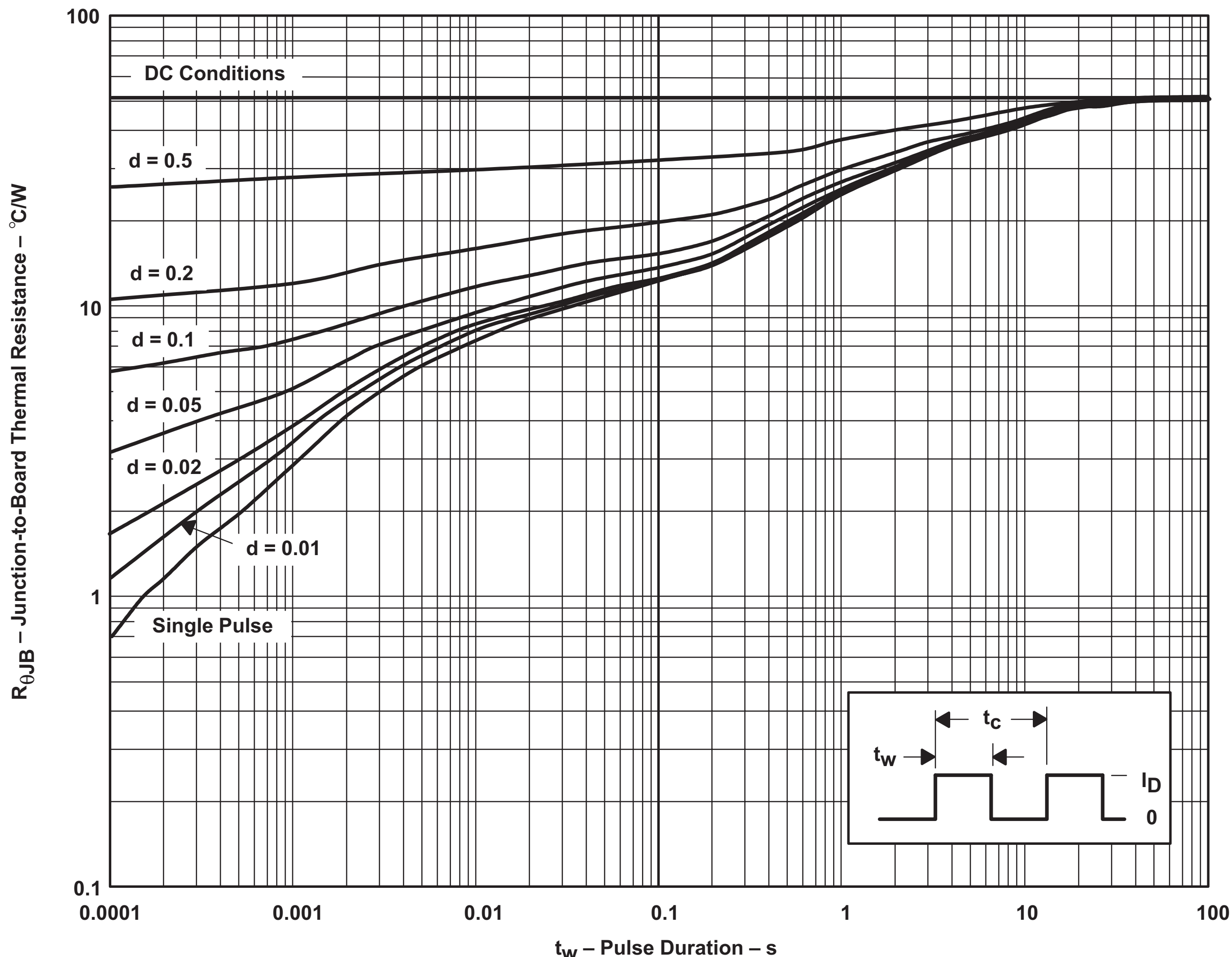


Figure 25

† Less than 10% duty cycle
‡ Device is mounted on a 24 in^2, 4 layer FR4 printed-circuit board.
§ Device is mounted in intimate contact with infinite heatsink.
¶ Less than 2% duty cycle

THERMAL INFORMATION



† Device is mounted on 24 in^2, 4-layer FR4 printed circuit board with no heat sink.

NOTE A: $Z_{\theta B}(t) = r(t)\,R_{\theta JB}$
t_w = pulse duration
t_c = cycle time
d = duty cycle = t_w/t_c

Figure 26

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